Preliminary



Designed for SDARS IF

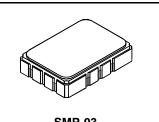
- SAW Diplexer 72.54 MHz / 80.46 MHz
- 5.0 X 7.0 mm Surface-Mount Case
- Complies with Directive 2002/95/EC (RoHS)

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Maximum DC Voltage Between any Two Terminals	0	VDC
Operating Temperature Range	-40 to +105	°C

SF2143B

72.54 / 80.46 MHz **SAW Diplexer**



SMP-03

Electrical Characteristics TDM1 Filter

Characteristic		Sym	Notes	Min	Тур	Max	Units
Nominal Center Frequency				72.54			MHz
Passband Width	1 dB	BW ₁	1		4.4		MHz
	15 dB	BW ₁₅	1		6.4		MHz
	30 dB	BW ₃₀			7.3		MHz
Passband Minimum Insertion Loss (including matching	network) at f _C	IL _{MIN}			14.6		dB
Amplitude Ripple, f _C ± 1.85 MHz					1.0		dB _{P-P}
Attenuation Relative to Minimum Insertion Loss	50.00 to 66.48 MHz				46		dB
	66.48 to 68.08 MHz				40		dB
	77.30 to 78.60 MHz				41		dB
	78.60 to 86.50 MHz				43		dB
	86.50 to 91.50 MHz				53		dB
	91.50 to 100.0 MHz				63		dB
Group Delay Ripple					90		ns _{P-P}
Source Impedance, Differential				27	ohms or 200 ohms	3	
Load Impedance, Differential				1K ohms or 1.5K ohms			

Characteristic		Sym	Notes	Min	Тур	Max	Units
Nominal Center Frequency		f _C		80.46		MHz	
Passband Width	1 dB	BW ₁	1		4.5		MHz
	15 dB	BW ₁₅			6.5		MHz
	30 dB	BW ₃₀			7.2		MHz
Passband Minimum Insertion Loss (including the match	ning network) at f _C	IL _{MIN}			15.6		dB
Amplitude Ripple, f _C ± 1.85 MHz					1.9		dB _{P-P}
Attenuation Relative to Minimum Insertion Loss	50.00 to 74.39 MHz				44		dB
	74.39 to 75.99 MHz				34		dB
	85.21 to 86.50 MHz				44		dB
	86.50 to 91.50 MHz				46		dB
	91.50 to 100.0 MHz				57		dB
Group Delay Ripple					92		ns _{P-P}
Source Impedance, Differential					27 ohms or 200 ohi	ms	
Load Impedance, Differential					1K ohms or 1.5K oh	ims	
Case Style			6	SMP-03 7 x 5 mm Nominal Footprint		otprint	
Lid Symbolization (YY=year, WW=week, S=shift) See note 4			0		RFM SF2143	B YYWWS	

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

Notes:

- Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc. 1.
- 2.
- 3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
- 4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
- The design, manufacturing process, and specifications of this filter are subject to change. Tape and Reel Standard ANSI / EIA 481. 5.

6. 7.

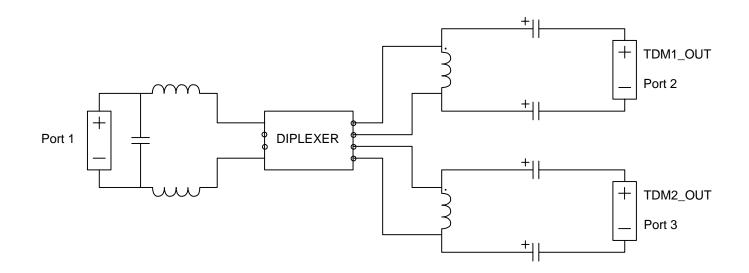
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Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design. US and international patents may apply. RFM, stylized RFM logo, and RF Monolithics, Inc. are registered trademarks of RF Monolithics, Inc.

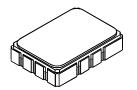
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Matching Circuit:

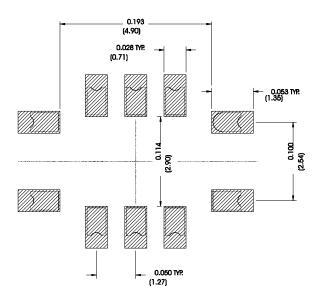


SMP-03 Case

10-Terminal Ceramic Surface-Mount Case 7 x 5 mm Nominal Footprint



Recommended PCB Footprint



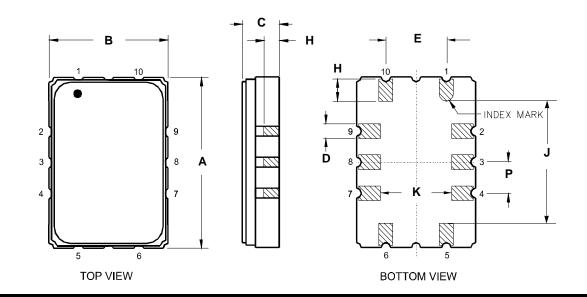
Case Dimen	Case Dimensions						
Dimension	mm			Inches			
	Min	Nom	Мах	Min	Nom	Max	
Α	6.80	7.00	7.20	0.268	0.276	0.283	
В	4.80	5.00	5.20	0.189	0.197	0.205	
С		1.65	2.00		0.065	0.079	
D	.47	0.60	.73	0.019	0.024	0.029	
E	2.41	2.54	2.67	0.095	0.100	0.105	
Н	0.87	1.0	1.13	0.034	0.039	0.044	
J	4.87	5.00	5.13	0.192	0.197	0.202	
К	2.87	3.00	3.13	0.113	0.118	0.123	
Р	1.14	1.27	1.40	0.045	0.050	0.055	

Electrical Connections

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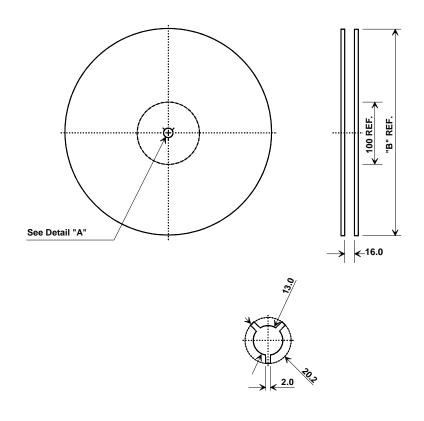
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		Connection	Terminals			
Port 1	Port 1 Input		1			
	Input		10			
Port 2	Outpu	ut TDM1	6			
	Outpu	ut TDM1	7			
Port 3	Output TDM2		4			
	Outpu	ut TDM2	5			
	Grou	nd	All others			
	Materials					
Solder Pad Plating 0.3 to 1.0 µm Gold over 1.27		0.3 to 1.0 µm Gold over 1.27	to 8.89 µm Nickel			
Lid Plating 2.0 to 3.0 µm Nickel		2.0 to 3.0 µm Nickel				
Body Al ₂ O ₃ Ceramic		Al ₂ O ₃ Ceramic				
Pb Free	Pb Free					



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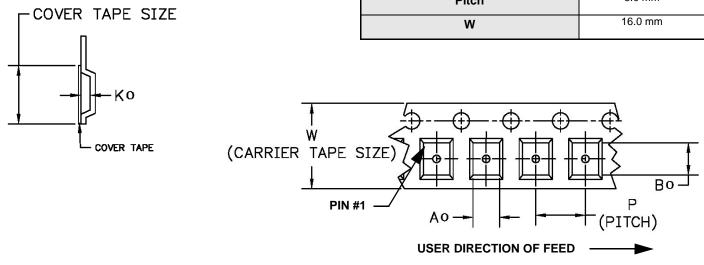
Tape and Reel Specifications



"В "		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	2000

COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions				
Ао	5.5 mm			
Во	7.5 mm			
Ко	2.0 mm			
Pitch	8.0 mm			
W	16.0 mm			



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